



CMS Binary Chip (CBC) status

130nm CMOS chip for short strip readout at sLHC

contents

introduction to CBC architecture

first test results

ACES Workshop, March 2011
Mark Raymond, Imperial College.

CBC architecture

targeted at phase II short strips

~2.5 – 5 cm

not contributing to L1 trigger

binary unparsified architecture

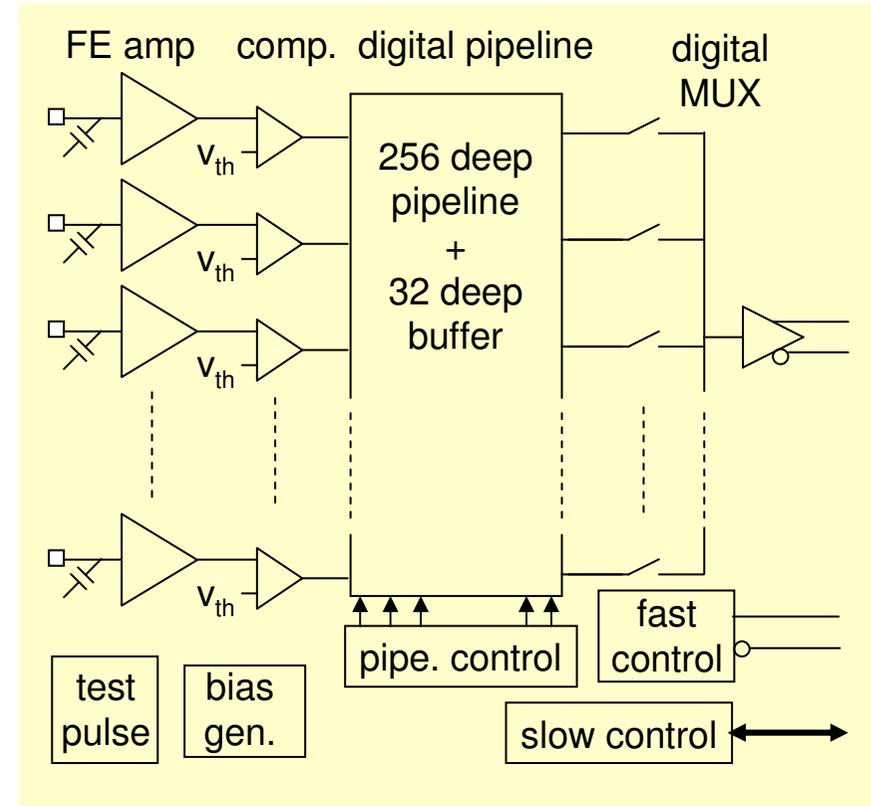
chip & system simplicity, low power

main functional blocks

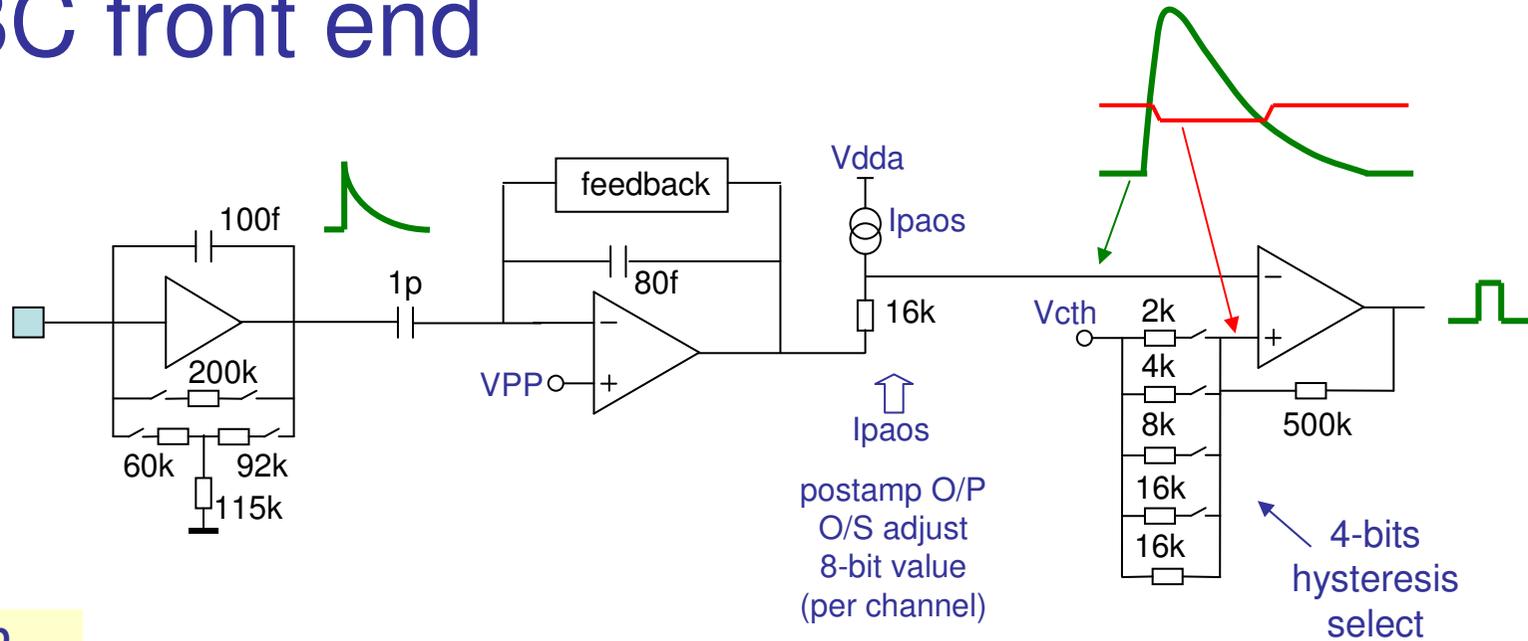
- fast front end amplifier – 20 nsec peaking
- comparator with programmable threshold trim
- 256 deep pipeline (6.4 us)
- 32 deep buffer for triggered events
- output mux and SLVS driver
- fast (SLVS) and slow (I2C) control interfaces

some target specs

- DC coupled to sensor – up to 1 uA leakage
- can be used for both sensor polarities
- noise: $< 1000e$ for $C_{\text{SENSOR}} \sim 5 \text{ pF}$
- power consumption
 $< 0.5 \text{ mW/channel}$ for $C_{\text{SENSOR}} \sim 5 \text{ pF}$



CBC front end



preamp

resistive feedback absorbs I_{leak}
 T network for holes
 Rf.Cf implements short
 20ns diff. time constant
 (good for no pile-up)

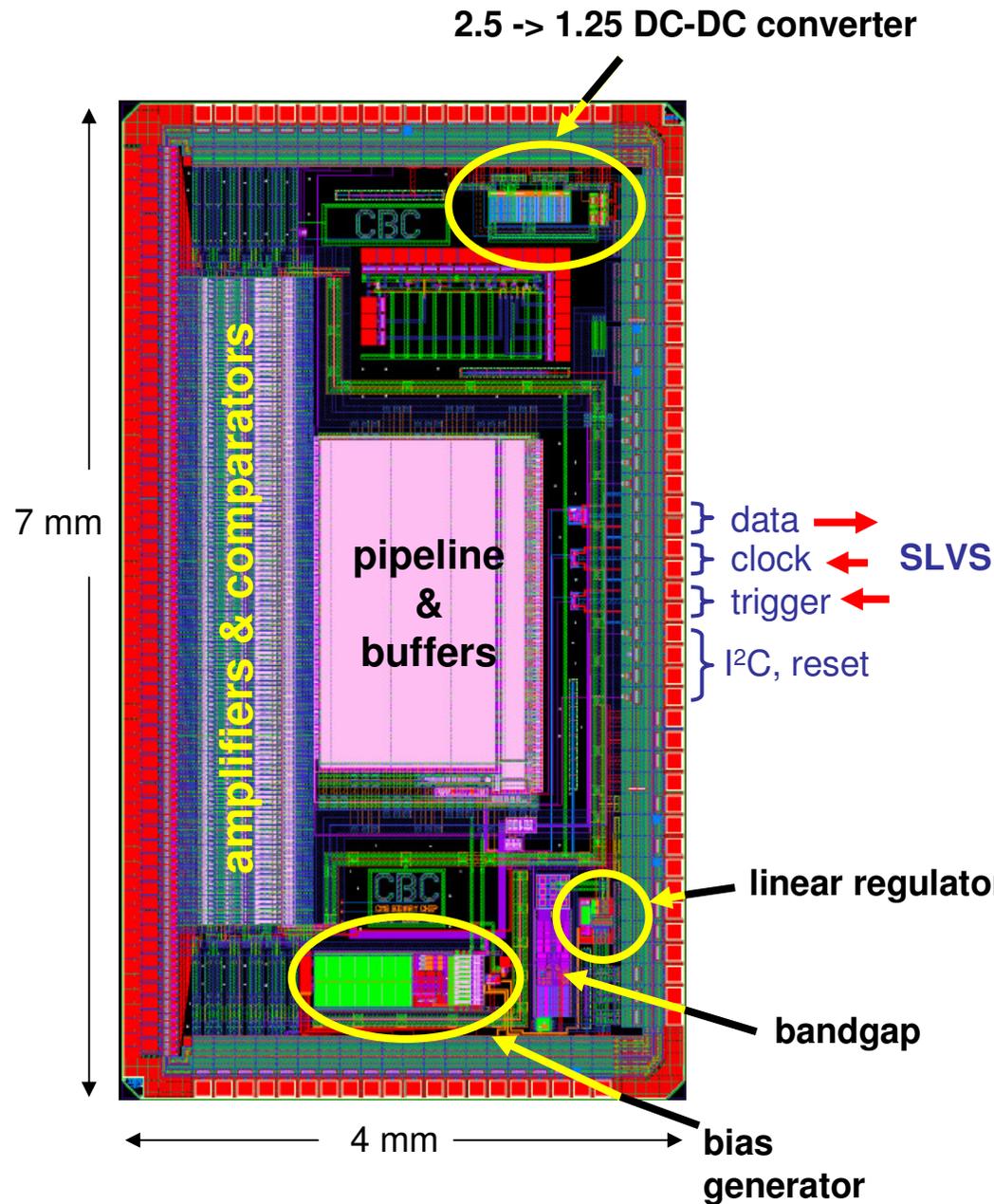
postamp

provides gain and int. time constant
 $\sim 50 \text{ mV} / \text{fC}$
 AC coupling removes I_{leak} DC shift
 individually programmable O/P DC level
 implements channel threshold tuning
 8-bits, 0.8 mV / bit, 200 mV range

comparator

global threshold
 (indiv. tuning at postamp O/P)
 programmable hysteresis)

CBC layout



128 inputs, 50 μm pitch
back edge pads mostly power
but also data out, clock and trigger in
I2C slow control

power features included to study
DC-DC switched capacitor
CERN (M.Bochenek et al)
low dropout linear regulator
uses CERN bandgap (P.Moreira)

test features

top edge: dummy channel with access
to signals along analog chain

bottom edge: access to all bias generator
outputs

status

chip design begun ~March 2009 in 130nm IBM CMOS
Lawrence Jones (RAL engineer)

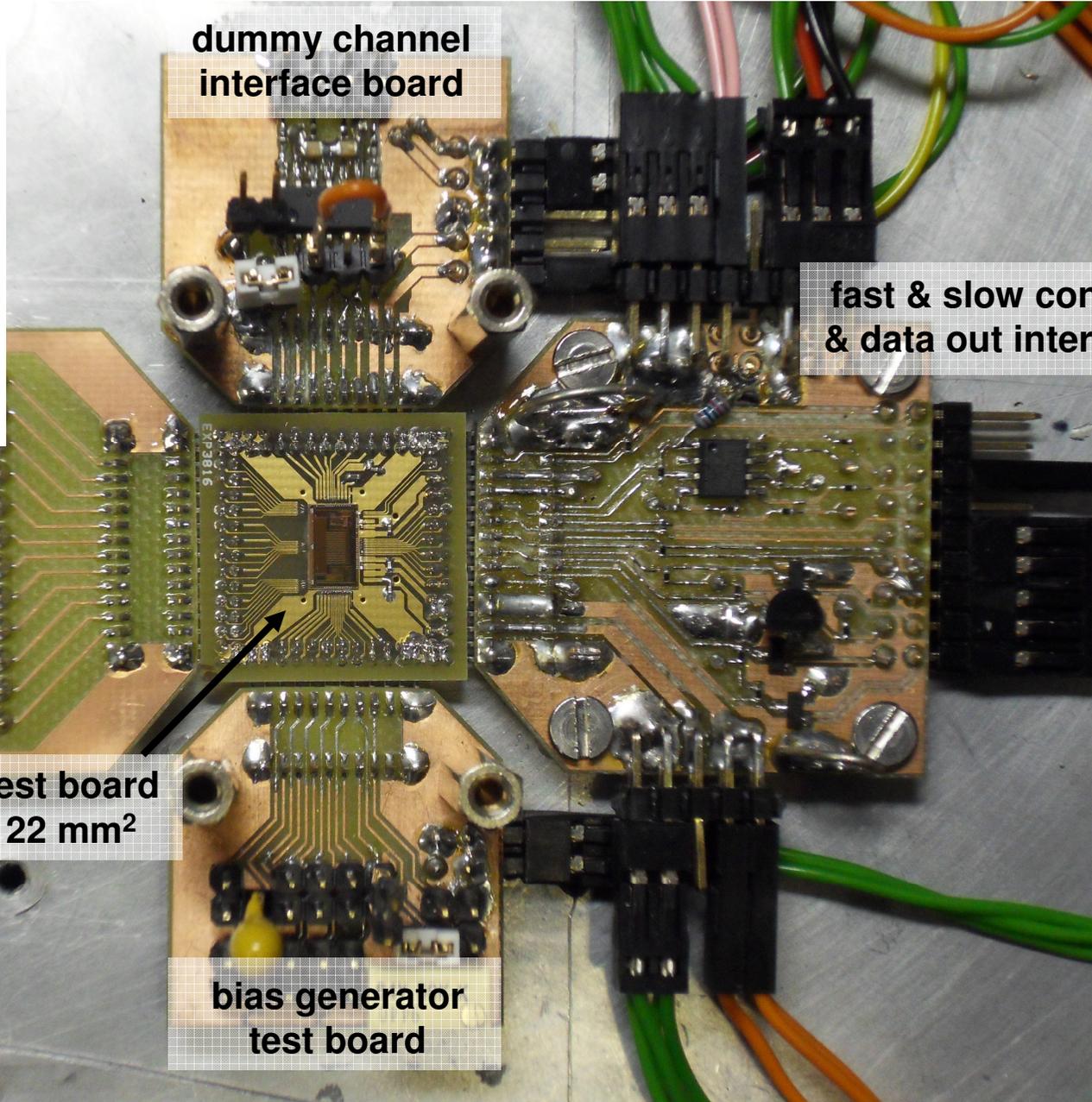
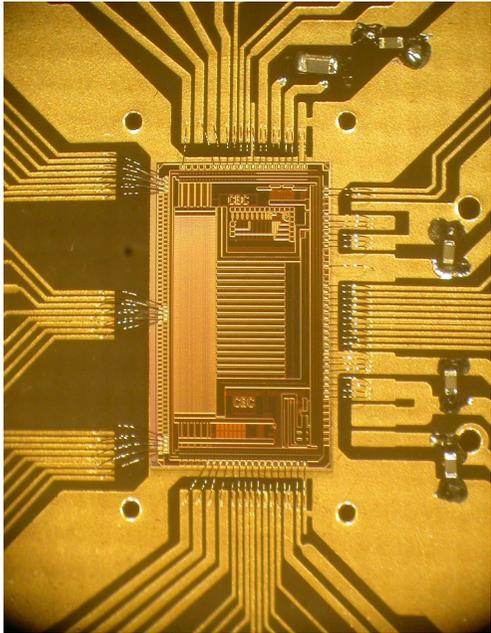
submission: July 2010, expected turnaround
~ 3 months (~ end October)

unexpected delays
foundry busy with volume production
wafers available just before Xmas – not diced till after

=> chips under test since 14th February

results here from a handful of die
not all features yet investigated
... and nothing at a thorough level

test setup



dummy channel interface board

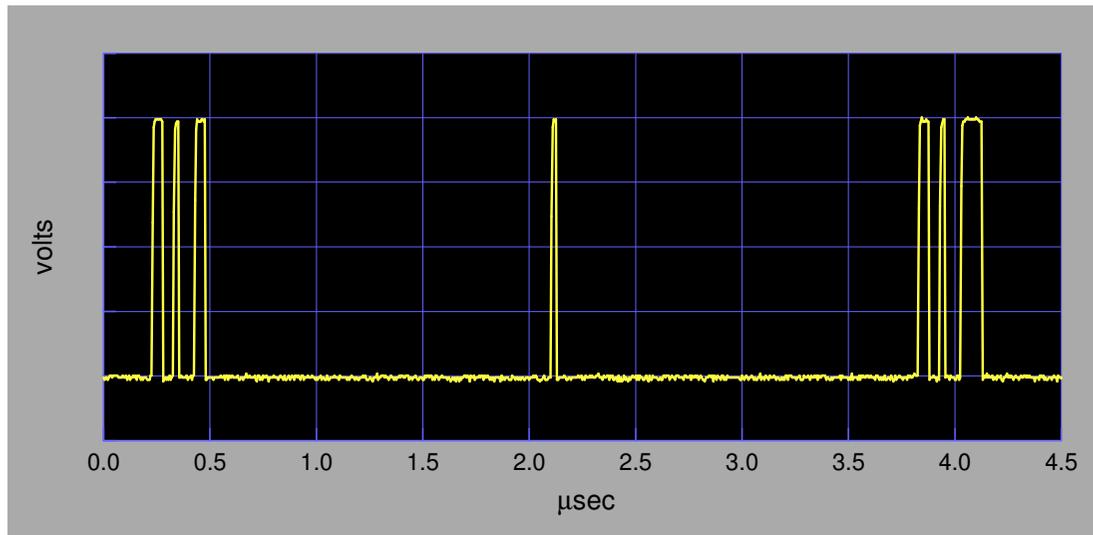
fast & slow control & data out interface

test charge injection

CBC test board
~ 22 x 22 mm²

bias generator test board

output data frame pictures



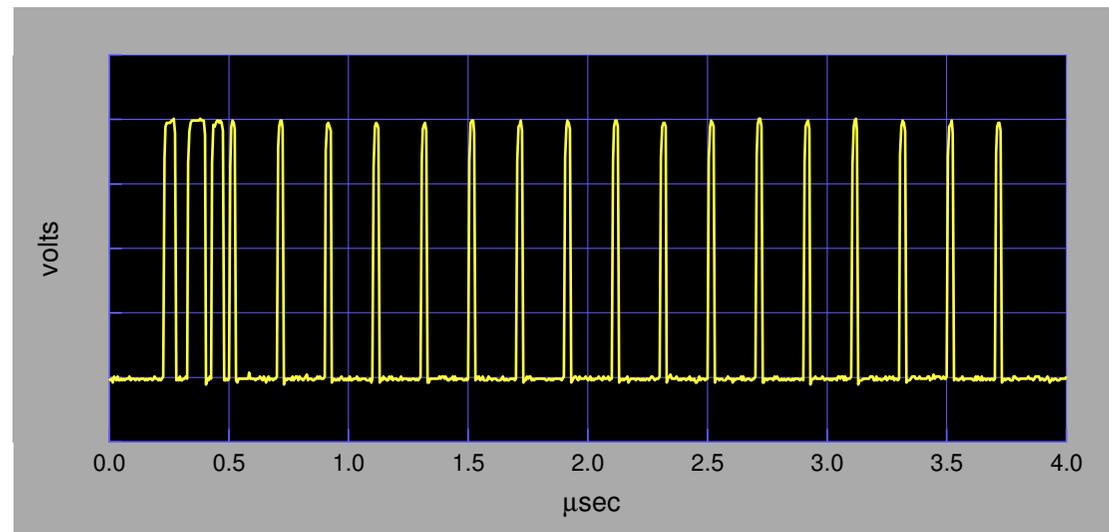
← 2 consecutive data frames (2 headers)
1 fC signal injected on one channel

data frame comprises:

- 2 start bits
- 2 error bits (latency, fifo overflow)
- 8 bit pipeline address
- 128 channel bits

16 "hits" produced by on-chip
test pulse feeding every 8th
channel

signal size ~ 1.5 fC

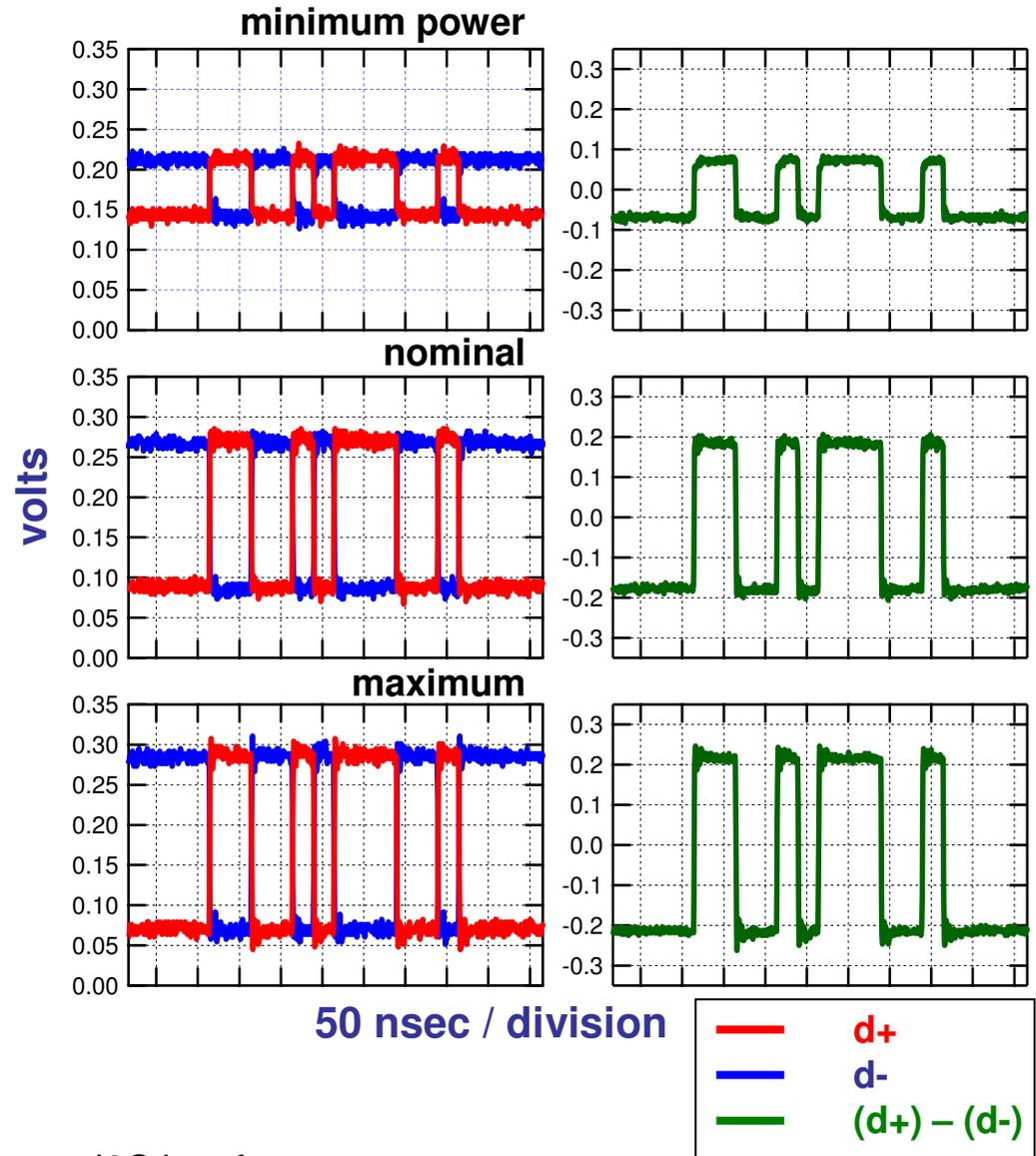
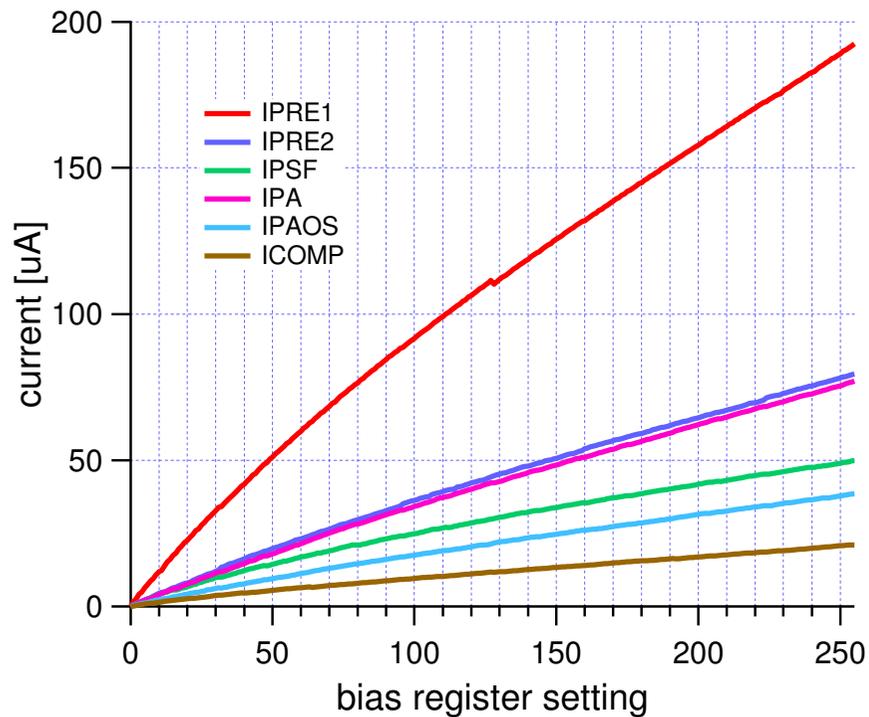


fast and slow control interfaces

SLVS interface circuits provided by CERN
S. Bonacini, K.Kloukinas

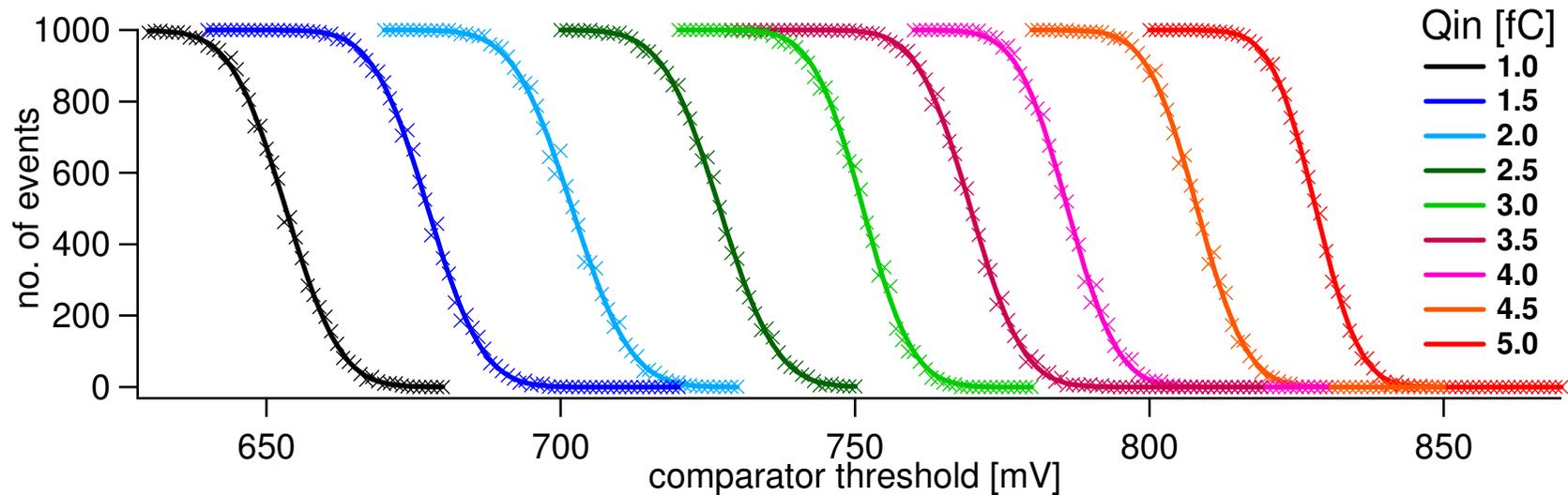
programmable current (amplitude)
0.5 – 2.0 mA

pictures show digital header



I2C interface to programme
currents
voltages
operational modes
128 individual channel offsets

S-curves & gain



can extract gain and noise by plotting S-curves

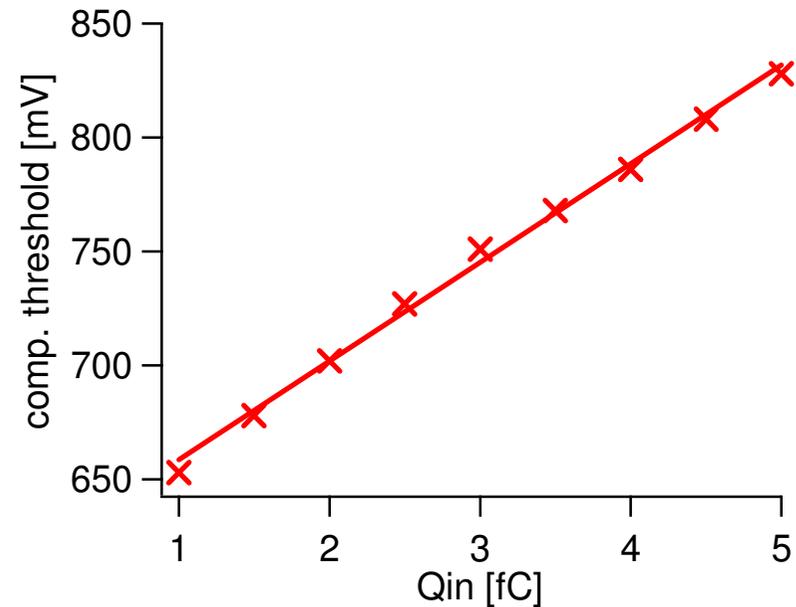
sweep comparator threshold over range from where it fires all time to not at all

count no. of events exceeding threshold

repeat for different values of injected charge

plot S-curve mid-point vs. Q_{in} to give gain →

-> gain ~ 50 mV / fC (close to expectation)

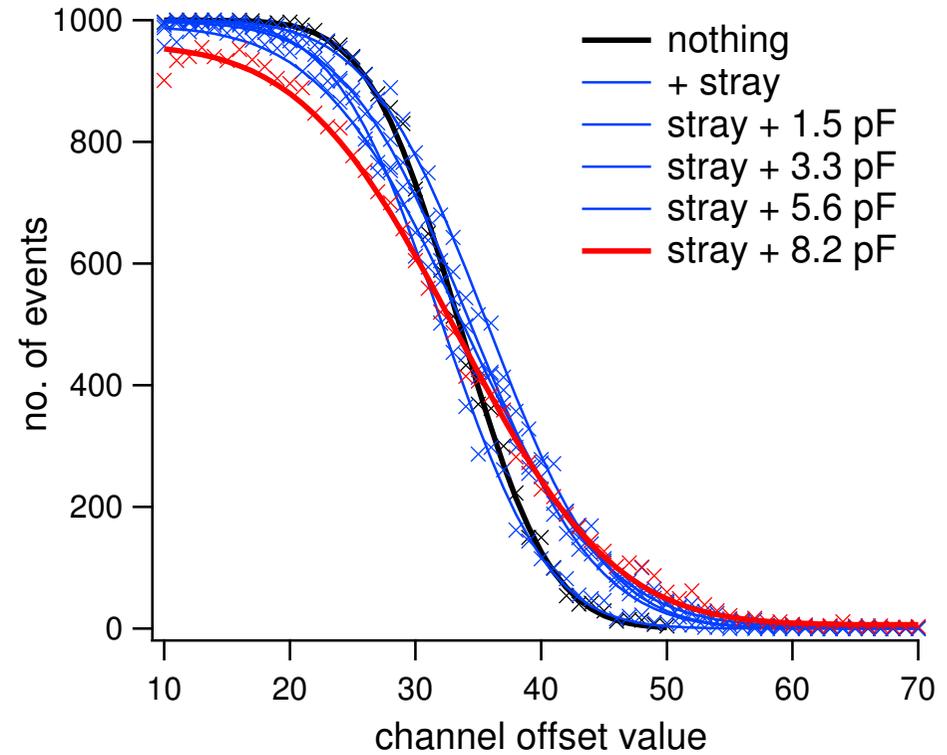
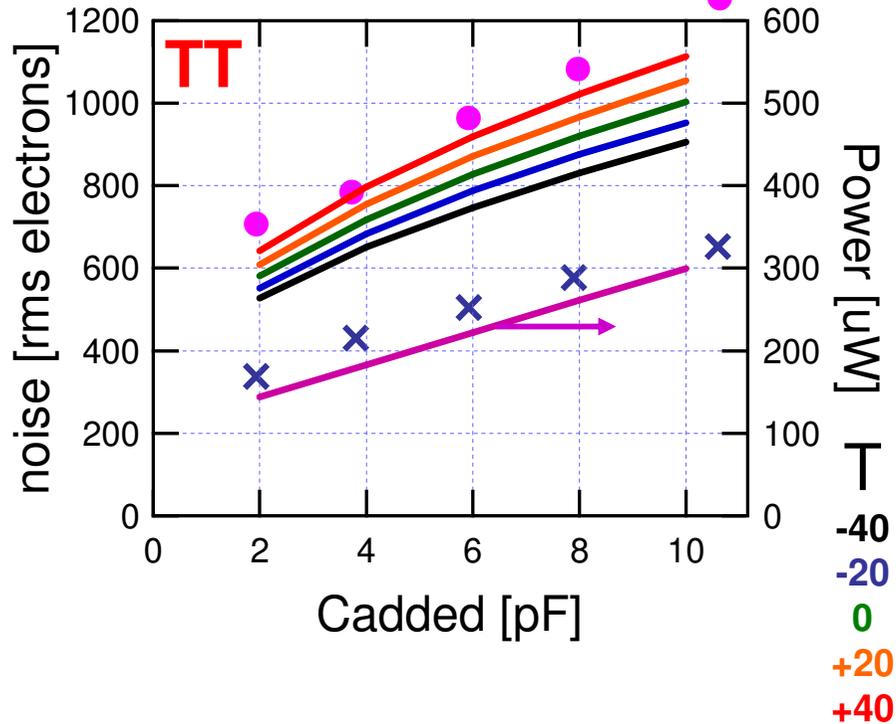


noise

measure from fit to S-curves

technique needs refining
(accurate determination of stray cap.)

but results look believable
close to (bit worse than) expectation



← lines show simulation
(for different temperatures)

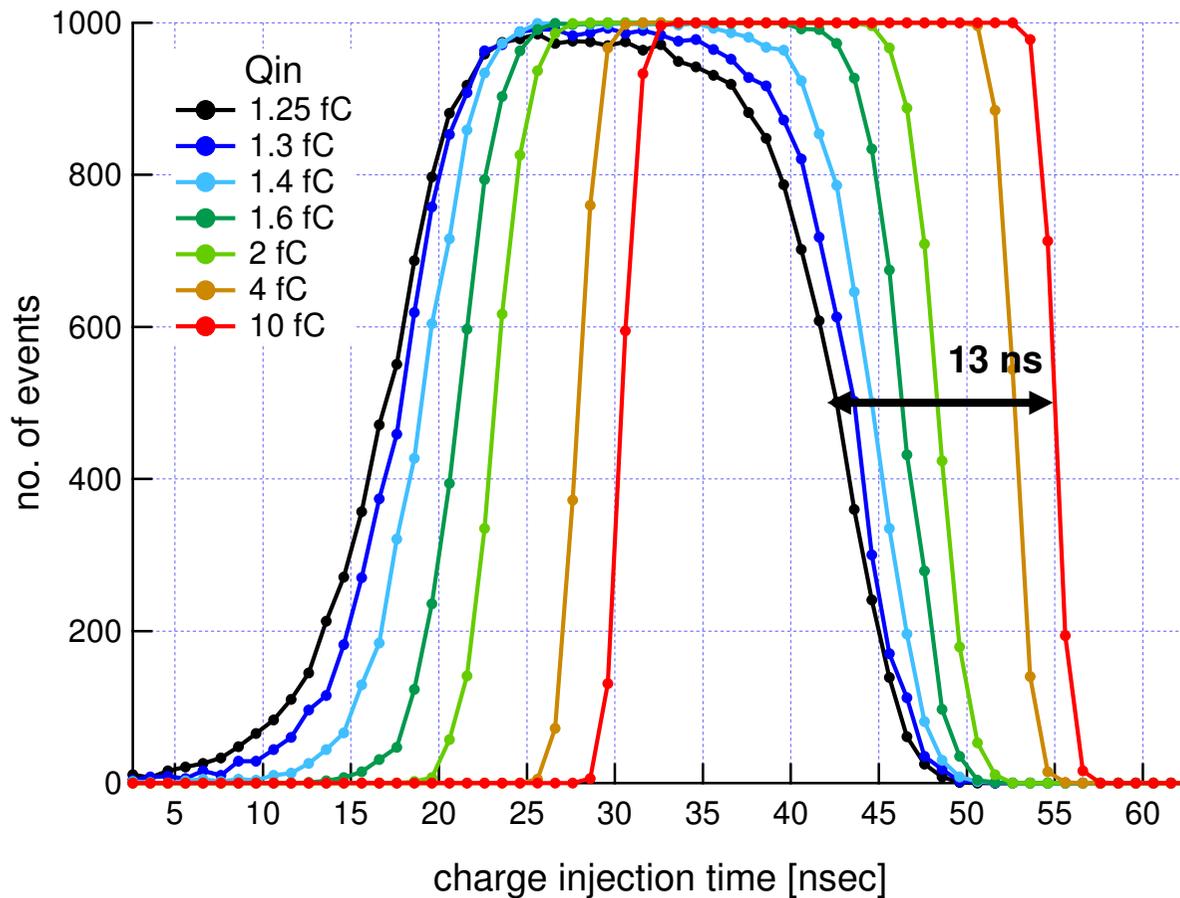
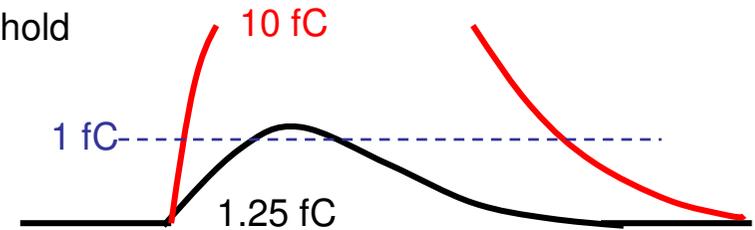
dots ● show noise measurements
at × power/channel

(power tuned to maintain same pulse
shape for different sensor capacitance)

timewalk

measure by triggering same pipeline timeslice and sweeping charge injection time

smaller signals have to be injected earlier to exceed comp. threshold within the sensitive (triggered) period



comparator threshold at 1 fC

timewalk specification:
<16 ns between 1.25 and 10 fC
signals with threshold at 1 fC

power consumption

target

0.5 mW / channel based on

analogue

150 - 300 uW depending on sensor capacitance

digital

~ **300 uW** based on rough estimates
(including 150 uW contingency)

measured

analogue

have been biasing up to now in line with simulation

150 - 300 μ W / channel

digital

$I_{VDD} = 2.8 - 4.5$ mA for whole chip depending on SLVS bias setting

< 50 μ W / channel

no measurable dependence on L1 trigger rate (0 – 100 kHz)

digital circuitry functions correctly down to $V_{DDD} = 0.9$ V

total

200 – 350 uW / channel

significantly less than original design target

summary

CBC seems to be working well

still early days, but already seems clear that enough is working to allow us to learn as much as we need to from this prototype

- works for both polarities

- noise, gain, timewalk close to expectation

- power consumption lower than estimated

- powering features verified functional (see backup)

a long testing programme ahead, including

- powering options studies - supply sensitivity with/without various on-chip options

- temperature effects

- tests with sensors

- radiation: ionizing & SEU sensitivity

- test beam

future directions – currently looking at:

- bump-bonded version – allows to integrate pitch adaption to sensor on hybrid

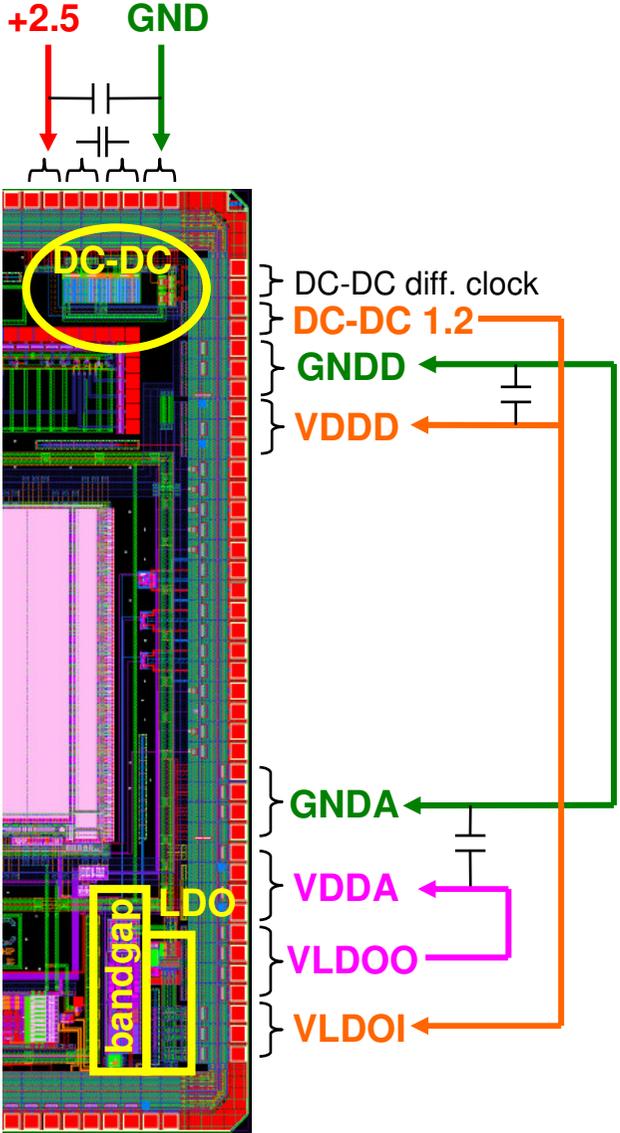
- 256 channel version with “2-in-1” triggering features (talk tomorrow)

CBC documentation:

http://icva.hep.ph.ic.ac.uk/~dmray/CBC_documentation/

EXTRA

powering features



DC-DC switched cap. – CERN (M.Bochenek et al)

converts 2.5 -> 1.2
 can use 1.2 to provide CBC digital rail (**VDDD**)
 and to feed LDO input (**VLDOI**)

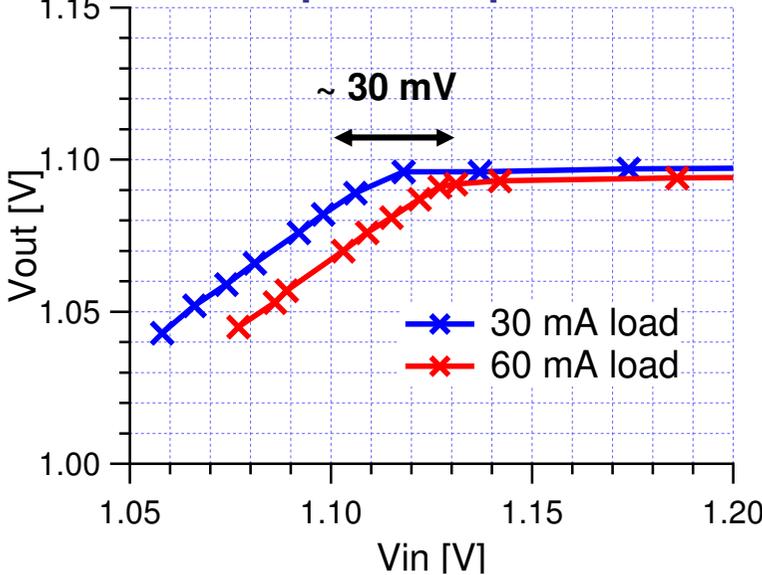
have powered up and observed functionality - no detailed study

LDO linear regulator

regulates 1.2V input to 1.1V output (**VLDOO**)
 can use to power analog circuitry (**VDDA**)
 (analog front end designed for 1.1V operation)
 should provide good power supply rejection
 uses **CERN bandgap circuit** (P.Moreira) for ref. voltage

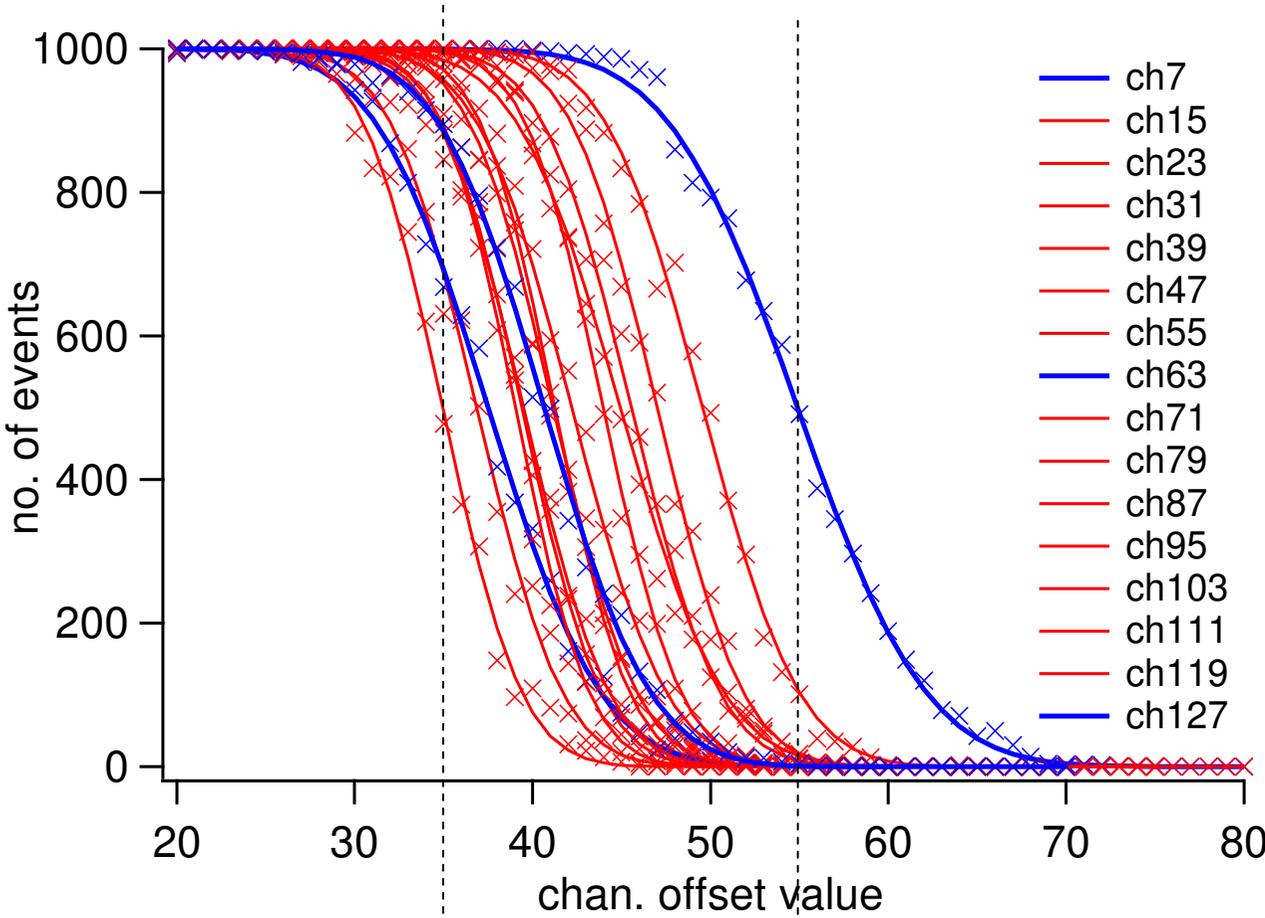
also appears to be functioning ok – again no detailed study

LDO output vs. input



dropout ~ 30 mV
 at 60 mA load
 (normal analogue
 current < 30 mA)

channel uniformity



can investigate using on-chip test charge injection

(though don't know how uniform test capacitors are)

sweep channel offsets for all 16 channels simultaneously

spread ~ 20 offset units
= 17 mV (0.34 fC)

note: blue channels are those bonded out to board
=> higher capacitance (noise)

testing programme

baseline performance (conventional (clean) powering scheme)

digital functionality

fast (Ck/T1 - SLVS) & slow control (I2C) interfaces setup and operation

analogue functionality

amplifier

pulse shape, noise, linearity,..

C_{IN} dependence, signal polarity dependence, across chip & chip-to-chip uniformity

leakage current tolerance

comparator

timewalk, threshold tuning and uniformity, hysteresis

all above will depend on bias generator settings

=> large parameter space to cover

power consumption

lots to study

have only scratched the surface so far

powering options studies

supply sensitivity with/without various on-chip options

longer term

temperature effects (~ all of above vs. T)

tests with sensors

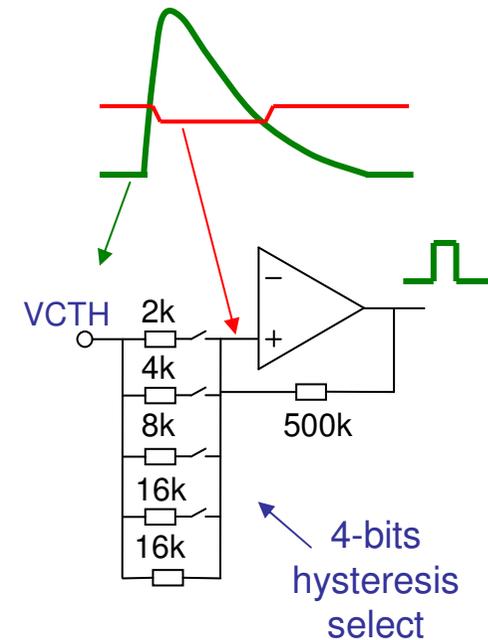
radiation: ionizing & SEU sensitivity

test beam

problems so far

not everything perfect – a couple of things have shown up so far

- 1) global comparator threshold voltage output (VCTH)
 - get interaction between multiple channels and VCTH
 - comparator has 500k feedback resistor (for hysteresis)
 - but 128 x 500k resistors in parallel -> 4k (not so big)
 - so VCTH gets pulled around if many channels switch at once
 - would not have shown up on test chip with just a few channels
 - can be fixed by providing external voltage
 - probably not difficult to fix by design
- 2) another of the bias generator outputs needs external decoupling
 - ~ similar effect associated with postamplifier
- 2) dummy analogue channel doesn't provide clean signals
 - can be used to study DC behaviour, but transient response shows ringing
 - may be due to test board layout – coupling between outputs and inputs
 - will investigate further
 - (not really an issue – but would have been if chip had not worked so well)



CBC-to-GBT interface

put e-port in separate GBT interface chip

incorporates circuitry to combine CBC data streams

extra chip on FE hybrid but could offer some future flexibility

